AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claim 1 (Previously Presented): A slurry for cutting a silicon ingot, comprising abrasive grains and a basic material, wherein:

the basic material is alkaline metal hydroxide, alkaline earth hydroxide or mixtures thereof;

a content of the basic material is at least 3.5% by mass based on a total mass of a liquid component of the slurry;

the slurry contains organic amine in a mass ratio of 0.5 to 5.0 with respect to water in the liquid component of the slurry; and

pH of the slurry is 12 or more.

Claim 2 (Currently Amended): A method of cutting a silicon ingot using a slurry for cutting a silicon ingot, the method comprising contacting the silicon ingot with the slurry and cutting the silicon ingot,

wherein the slurry comprises ~~comprising~~ abrasive grains and a basic material, and wherein:

the basic material is alkaline metal hydroxide, alkaline earth hydroxide or mixtures thereof;

a content of the basic material is at least 3.5% by mass based on a total mass of a liquid component of the slurry;

the slurry contains organic amine in a mass ratio of 0.5 to 5.0 with respect to water in the liquid component of the slurry;

pH of the slurry is 12 or more; and

the slurry is used at 65°C to 95°C.

Claim 3 (New): The slurry according to claim 1, wherein the average grain diameter of the abrasive grains is 1 μm to 60 μm.

Claim 4 (New): The slurry according to claim 1, wherein the organic amine is present in a mass ratio of 1.0 to 4.0 with respect to the water in the liquid component of the slurry.

Claim 5 (New): The slurry according to claim 1, wherein the water is present in an amount of 10% by mass to 40% by mass with respect to the total mass of the slurry.

Claim 6 (New): The method according to claim 2, wherein the average grain diameter of the abrasive grains is 1 μm to 60 μm.

Claim 7 (New): The method according to claim 2, wherein the organic amine is present in a mass ratio of 1.0 to 4.0 with respect to the water in the liquid component of the slurry.

Claim 8 (New): The method according to claim 2, wherein the water is present in an amount of 10% by mass to 40% by mass with respect to the total mass of the slurry.

Claim 9 (New): The method according to claim 2, wherein the step of cutting the silicon ingot is conducted with a band saw, a wire saw, a multi-band saw, a multi-wire saw, an outer edge cutting apparatus or an inner edge cutting apparatus.

Claim 10 (New): The slurry according to claim 1, wherein the slurry further comprises a coolant.

Claim 11 (New): The method according to claim 2, wherein the slurry further comprises a coolant.